## UL Product iQ®



## Wiring, Printed - Component

## **COMPANY**

## **Toptek PCB Co Ltd**

A417, Building 1, Hedong Industrial Zone Xin'an Street Bao'an 49 District Shenzhen, Guangdong 518101 China

E521933

Cond Width					Max		Max								
	Min Cond			SS/ Area date Surface			Assembly Solder Solo			der Oper			Meets	С	
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Lim	its	Temp	Flame	UL796	Т
Туре	mm	mm	mic	DSO	mm	2022- 01-01	Technology	Temp °C	Cycles	°C	sec	°C	Class	DSR	ı
Multilayer printed wiring boards															
TTP- 2	0.13	0.13	17 Int:34	DS	50.8	No	-	-	-	288	10	130	V-0	All	*
TTP- 3	0.08	0.15	17 Int:68	DS	50.8	No	-	-	-	288	10	130	V-0	All	*
TTP- 5	0.10	0.10	17 Int:68	DS	25.4	No	-	-	-	288	20	130	V-0	All	*
TTP- 8 (ASP 1)	0.075	0.075	12 Int:102	DS	76.2	Yes	Yes	260	4	288	20	130	V-0	All	*
Single layer metal base printed wiring boards															
TTP- 7	0.20	0.20	17	SS	50.8	No	-	-	-	288	10	130	V-0	All	0
Single	layer p	rinted v	viring bo	ards											
TTP- 1	0.10	0.10	17	DS	50.8	No	-	-	-	270	10	130	V-0	All	-
TTP-	0.10	0.10	17	DS	25.4	No	-	-	-	288	20	130	V-0	All	*
Single	layer Pr	inted W	/iring Bo	ards											

	TTP-	0.075	0.075	12	DS	76.2	Yes	Yes	260	4	288	20	130	V-0	All	*
	6 (ASP 1)															
ı	')															

<sup>\* -</sup> CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification.

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